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PCN: PCN-PLP-42936-025-0

Product Change Notice

Issue Date: July 20, 2017

Change Type:

- Assembly site addition (ASE CHINA).

Parts Affected:

Device	Package Size	Package	Pin Count
BCM8073CIFBG	19X19	FBGA	324
BCM8073BIFBG	19X19	FBGA	324
BCM8727BIFBG	19X19	FBGA	324
BCM8727BIFB	19X19	FBGA	324
BCM8727CIFBG	19X19	FBGA	324
BCM8727MBIFBG	19X19	FBGA	324
BCM8727MCIFBG	19X19	FBGA	324
BCM8722CIFBG	19X19	FBGA	324
BCM8722BIFBG	19X19	FBGA	324
BCM5941CKFBG	19X19	FBGA	324

Description and Extent of Change:

- Add ASE China as an additional assembly supplier for the above devices.
- The extent of the change is minimal. ASE China has internally qualified the package type is in volume production for the above package technology

Reasons for Change:

- Manufacturing flexibility

Effect of Change on Fit, Form, Function, Quality, or Reliability:

- No impact on form, fit and function

Effective Date of Change:

- Product shipments using this change will begin week of September 29, 2017

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Qualification Data:

Pkg Qualification Reference# PQ01737
Fab Technology : 130nm G
Package Type : FBGA
Package Size : 21mm x 21mm
Lead Count : 400
Bond Wire : COPPER: 99.95% Cu/Pd-plated (3N; NMC)

Stress Test	**Condition**	**Read points Cycles / Hrs.**	**Sample Size**	**Requirements**	**Results (# fail/ss)**
Precondition	MSL3 JESD22-A113E		260 units	0 failures	0 / 260
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	76 units	0 failures	0 / 76
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	500 cycles	76 units	0 failures	0 / 76
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	76 units	0 failures	0 / 76
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	76 units	0 failures	0 / 76

Pkg Qualification Reference# PQ01842
Fab Technology : 65nm LP
Package Type : FBGA
Package Size : 21mm x 21mm
Lead Count : 400
Bond Wire : COPPER: 99.95% Cu/Pd-plated (3N; NMC)

Stress Test	**Condition**	**Read points Cycles / Hrs.**	**Sample Size**	**Requirements**	**Results (# fail/ss)**
Precondition	MSL3 JESD22-A113E		260 units	0 failures	0 / 260
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	76 units	0 failures	0 / 76
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	500 cycles	76 units	0 failures	0 / 76
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	76 units	0 failures	0 / 76
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	76 units	0 failures	0 / 76

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Pkg Qualification Reference# PQ01936
Fab Technology : 65nm LP
Package Type : FBGA
Package Size : 21mm x 21mm
Lead Count : 459
Bond Wire : COPPER: 99.95% Cu/Pd-plated (3N; NMC)

Stress Test	**Condition**	**Read points** **Cycles / Hrs.**	**Sample Size**	**Requirements**	**Results (# fail/ss)**
Precondition	MSL3 JESD22-A113E		228 units	0 failures	0 / 228
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	76 units	0 failures	0 / 76
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	500 cycles	76 units	0 failures	0 / 76
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	76 units	0 failures	0 / 76
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	76 units	0 failures	0 / 76

Pkg Qualification Reference# PQ02441
Fab Technology : 90nm G
Package Type : FBGA
Package Size : 19mm x 19mm
Lead Count : 441
Bond Wire : COPPER: 99.95% Cu/Pd-plated (3N, NMC)

Stress Test	**Condition**	**Read points** **Cycles / Hrs.**	**Sample Size**	**Requirements**	**Results (# fail/ss)**
Precondition	MSL3 JESD22-A113E		228 units	0 failures	0 / 228
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	76 units	0 failures	0 / 76
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	300 cycles	76 units	0 failures	0 / 76
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	76 units	0 failures	0 / 76
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	76 units	0 failures	0 / 76

Pkg Qualification Reference# PQ00696

Fab Technology : 130nm G
Package Type : FBGA
Package Size : 21mm x 21mm
Lead Count : 400
Bond Wire : GOLD: 99.99% Au (4N)

Stress Test	**Condition**	**Read points Cycles / Hrs.**	**Sample Size**	**Requirements**	**Results (# fail/ss)**
Precondition	MSL3 JESD22-A113E		265 units	0 failures	0 / 265
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	76 units	0 failures	0 / 76
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	500 cycles	76 units	0 failures	0 / 76
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	76 units	0 failures	0 / 76
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	76 units	0 failures	0 / 76

Pkg Qualification Reference# PQ01197

Fab Technology : 65nm LP
Package Type : FBGA
Package Size : 21mm x 21mm
Lead Count : 336
Bond Wire : GOLD: 99% Au/1% Pd (2N)

Stress Test	**Condition**	**Read points Cycles / Hrs.**	**Sample Size**	**Requirements**	**Results (# fail/ss)**
Precondition	MSL3 JESD22-A113E		244 units	0 failures	0 / 244
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	76 units	0 failures	0 / 76
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	500 cycles	76 units	0 failures	0 / 76
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	76 units	0 failures	0 / 76
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	76 units	0 failures	0 / 76

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Pkg Qualification Reference# PQ02206
Fab Technology : 90nm G
Package Type : FBGA
Package Size : 21mm x 21mm
Lead Count : 400
Bond Wire : GOLD: 99.99% Au (4N)

Stress Test	**Condition**	**Read points** **Cycles / Hrs.**	**Sample Size**	**Requirements**	**Results (# fail/ss)**
Precondition	MSL3 JESD22-A113E		260 units	0 failures	0 / 260
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	76 units	0 failures	0 / 76
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	500 cycles	76 units	0 failures	0 / 76
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	76 units	0 failures	0 / 76
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	76 units	0 failures	0 / 76

Please contact your Broadcom Limited field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.